Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.025”**

**ANODE**

**.017 x .017”**

**BACKSIDE IS CATHODE**

**.025”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .017” X .017”**

**Backside Potential: CATHODE**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .025” X .025” DATE: 8/9/21**

**MFG: MICROSEMI / CDI THICKNESS .008” P/N: THZ9R1A05**

**DG 10.1.2**

#### Rev B, 7/19/02